

deposited alternately one on another, the interlaminar insulative resin layers each having through-holes having an inner wall filled with a plating layer having a surface to form a viahole having a diameter; wherein:

the surface of said plating layer extends out of the through-holes and lies in a substantially same level as the surface of the conductor circuit layer disposed in the interlaminar insulative resin layer in which the plating layer also lies;

at least one of the surfaces of the conductor circuits is roughened to a depth of 1 to 10 μm ; and

the thickness of said conductor circuit layer is less than a half of the viahole diameter.

9. A multilayer printed wiring board comprising conductor circuit layers each having a respective thickness and a surface and interlaminar insulative resin layers deposited alternately one on another, the interlaminar insulative resin layers each having through-holes having an inner wall filled with a plating layer having at least one surface to form a viahole having a diameter, wherein the thickness of said conductor circuit layer is less than a half of the viahole diameter and less than 25 μm and wherein at least one of the surfaces of the conductor circuits is roughened to a depth of 1 to 10 μm .

17. A multilayer printed wiring board comprising conductor circuit layers each with at least one surface wherein at least one of the surfaces of the conductor circuit layer

is roughened to a depth of 1 to 10 μm and interlaminar insulative resin layers deposited alternately one on another, the interlaminar insulative resin layers each having through-holes, having an inner wall wherein the inner wall is roughened, filled with a plating layer to form a viahole, wherein:

said roughened inner wall is covered with a roughened electroless plating layer; and

an inner space of said through-hole defined by the electroless plating layer and is filled with an electroplating layer.

REMARKS

Reconsideration and withdrawal of the rejections in the Office Action are respectfully requested in view of the amendments and following remarks.

Request for withdrawal of finality of the Office Action

Applicants respectfully request that the finality of the Office Action issued on January 8, 2003 be withdrawn. The finality of the Office Action is based on the position that Applicants' argument made in response to the Office Action of May 24, 2002 have been considered but are moot in view of the new grounds of rejection and that Applicant's amendment necessitated the new grounds of rejection and accordingly, the Office Action is made final.

Applicants respectfully submit that the finality of the Office Action is premature and